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Vishay Siliconix

# Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY <sup>d</sup>				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.042			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.060			
I <sub>D</sub> (A)	15			
Configuration	Single			



#### **FEATURES**

- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- AEC-Q101 Qualified
- Package with Low Thermal Resistance
- Material categorization:
  For definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>



FREE

ORDERING INFORMATION	
Package	TO-252
Lead (Pb)-free and Halogen-free	SQD15N06-42L-GE3

N-Channel MOSFET

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>		15	
Continuous Drain Current	T <sub>C</sub> = 125 °C	l <sub>D</sub>	10	
Continuous Source Current (Diode Conduct	tion) <sup>a</sup>	I <sub>S</sub>	15	Α
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	50	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18	
Single Pulse Avalanche Energy	L = U.1 MH	E <sub>AS</sub>	16.2	mJ
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	Р	37	W
	T <sub>C</sub> = 125 °C	$P_{D}$	11	VV
Operating Junction and Storage Temperatu	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	50	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	4	C/VV

### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR-4 material).

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	: V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.036	0.042	Ω
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 125 °C	-	-	0.075	
Duta Ocean Ocean Butalana		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 175 °C	-	-	0.090	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 125 °C	-	0.092	-	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 175 °C	-	0.110	-	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 10 A	-	0.048	0.060	
Forward Transconductance <sup>b</sup>	9fs	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 6 A		-	11	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	425	535	
Output Capacitance	Coss	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	95	120	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	40	50	
Total Gate Charge <sup>c</sup>	Qg			-	9.5	15	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 15 \text{ A}$	-	1.7	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	2.5	-	
Gate Resistance	$R_g$	f = 1 MHz		1.8	3.6	5.4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD}=30~V,~R_L=2~\Omega$ $I_D\cong 15~A,~V_{GEN}=10~V,~R_g=1~\Omega$		-	5	8	
Rise Time <sup>c</sup>	t <sub>r</sub>			-	10	15	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	13	20	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	8	12	
Source-Drain Diode Ratings and Char-	acteristics <sup>b</sup>	•			•		
Pulsed Current <sup>a</sup>	I <sub>SM</sub>				-	50	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> =	10 A, V <sub>GS</sub> = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 15 A, dl/dt = 100 A/μs		-	29	60	ns

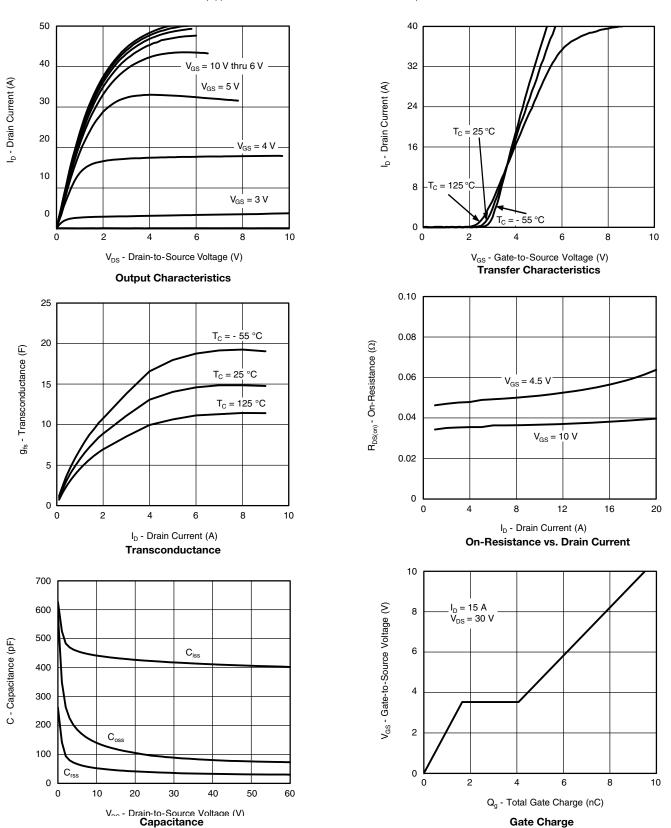
### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

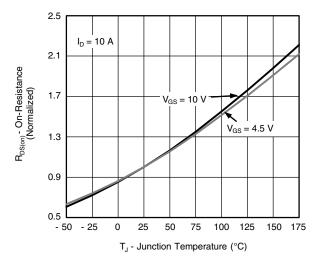


### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

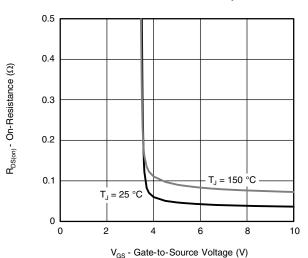




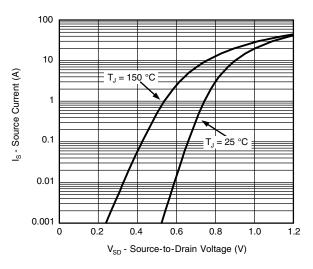
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



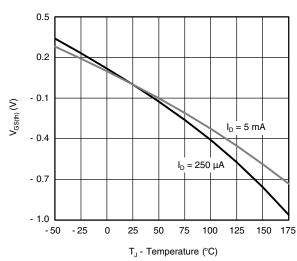
### On-Resistance vs. Junction Temperature



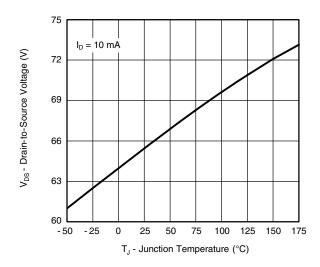
### On-Resistance vs. Gate-to-Source Voltage



### **Source Drain Diode Forward Voltage**



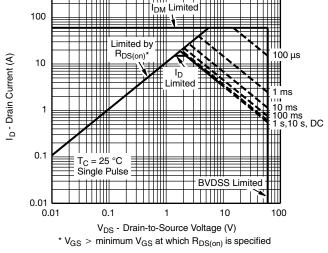
### Threshold Voltage



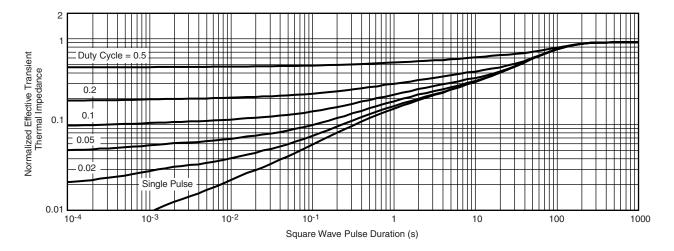
On-Resistance vs. Junction Temperature



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



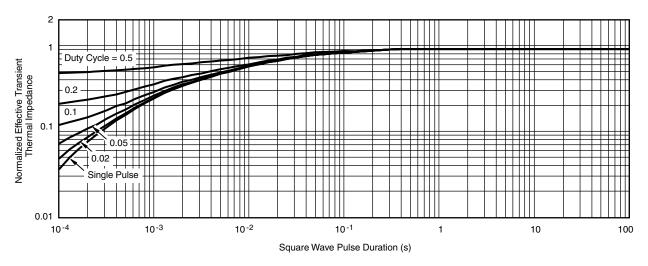
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

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### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

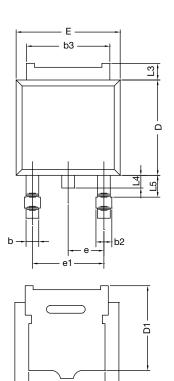
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

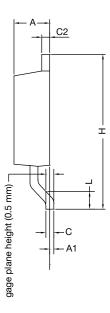
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppq?68880">www.vishay.com/ppq?68880</a>.



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## **TO-252AA Case Outline**





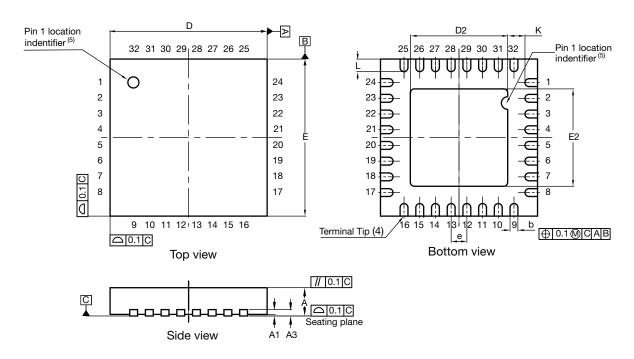
	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090	BSC	
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T13-0592-Rev. A, 02-Sep-13 DWG: 6019					

### Note

• Dimension L3 is for reference only.



## QFN32 5 x 5 Case Outline



DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.75	0.85	0.95	0.029	0.033	0.037	
A1	0.00	-	0.05	0.000	-	0.002	
A3		0.20 ref.		0.008 ref.			
b	0.18	0.25	0.30	0.007	0.010	0.012	
D	5.00 BSC			0.197 BSC			
D2	3.00	3.10	3.20	0.118	0.122	0.126	
е		0.50 BSC			0.020 BSC		
E		5.00 BSC			0.197 BSC		
E2	3.00	3.00 3.10 3.20		0.118	0.122	0.126	
K	0.20	-	-	0.008	-	-	
L	0.30	0.40	0.50	0.012	0.016	0.020	
N (3)	32				32		
Nd <sup>(3)</sup>	8			8			
Ne <sup>(3)</sup>	8			8			

#### Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5M. 1994
- (3) N is the number of terminals,
  - Nd is the number of terminals in X-direction and Ne is the number of terminals in Y-direction.
- (4) Dimension b applies to plated terminal and is measured between 0.15 mm and 0.30 mm from terminal tip
- (5) The pin #1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (6) Package warpage max. 0.05 mm

S14-2079-Rev. A, 20-Oct-14 DWG: 6027

Revision: 20-Oct-14 Document Number: 67244



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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Revision: 02-Oct-12 Document Number: 91000